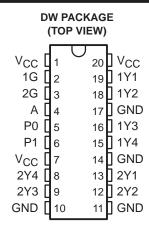
- Low Output Skew, Low Pulse Skew for Clock-Distribution and Clock-Generation Applications
- TTL-Compatible Inputs and Outputs
- Distributes One Clock Input to Eight Outputs
- Distributed V_{CC} and Ground Pins Reduce Switching Noise
- High-Drive Outputs (-48-mA I_{OH}, 48-mA I_{OI})
- State-of-the-Art EPIC-IIB™ BiCMOS Design Significantly Reduces Power Dissipation
- Packaging Options Include Plastic Small-Outline (DW) Packages



description

The CDC341 is a high-performance clock-driver circuit that distributes one (A) input signal to eight (Y) outputs with minimum skew for clock distribution. Through the use of the control pins (1G and 2G), the outputs can be placed in a low state regardless of the A input.

The propagation delays are adjusted at the factory using the P0 and P1 pins. These pins are not intended for customer use and should be strapped to GND.

The CDC341 is characterized for operation from 0°C to 70°C.

FUNCTION TABLE

	INPUTS		OUTI	PUTS
1G	2G	Α	1Y1-1Y4	2Y1-2Y4
Х	Х	L	L	L
L	L	Н	L	L
L	Н	Н	L	Н
н	L	Н	Н	L
Н	Н	Н	Н	Н

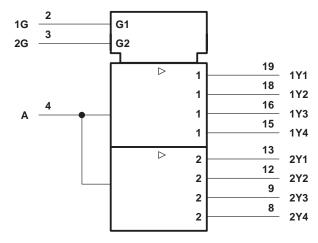


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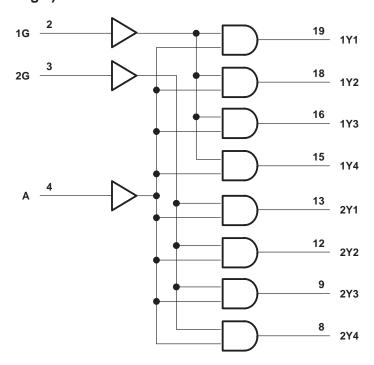


logic symbol†



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)





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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	0.5 V to 7 V
Input voltage range, V _I (see Note 1)	
Voltage range applied to any output in the high state or power-off state,	
V _O (see Note 1)	\dots -0.5 V to V _{CC} + 0.5 V
Current into any output in the low state, IO	96 mA
Input clamp current, I _{IK} (V _I < 0)	–18 mA
Maximum power dissipation at $T_A = 55^{\circ}C$ (in still air) (see Note 2)	1.6 W
Storage temperature range, T _{sta}	65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

recommended operating conditions (see Note 3)

			MIN	MAX	UNIT
Vcc	Supply voltage		4.75	5.25	V
VIH	High-level input voltage		2		V
VIL	Low-level input voltage			0.8	V
VI	Input voltage	0	VCC	V	
lOH	High-level output current			-48	mA
loL	Low-level output current			48	mA
f	Input clock frequency	One output bank loaded		80	MHz
fclock	input clock frequency	Both output banks loaded		40	IVITIZ
TA	Operating free-air temperature		0	70	°C

NOTE 3: Unused pins (input or I/O) must be held high or low.

^{2.} The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils. For more information, refer to the *Package Thermal Considerations* application note in the *ABT Advanced BiCMOS Technology Data Book*, literature number SCBD002.

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	_	Т	A = 25°C	;	MIN	MAX	UNIT		
PARAWETER	TEST CONDITIONS				TYP [†]	MAX	IVIIIV	IVIAA	UNIT
VIK	$V_{CC} = 4.75 \text{ V},$	I _I = -18 mA				-1.2		-1.2	V
	$V_{CC} = 4.75 \text{ V},$	$I_{OH} = -3 \text{ mA}$		2.5			2.5		
Voн	$V_{CC} = 5 V$,	$I_{OH} = -3 \text{ mA}$		3			3		V
	$V_{CC} = 4.75 \text{ V},$	$I_{OH} = -48 \text{ mA}$		2			2		
V _{OL}	$V_{CC} = 4.75 \text{ V},$	$I_{OL} = 48 \text{ mA}$						0.5	V
lį	$V_{CC} = 5.25 \text{ V},$	$V_I = V_{CC}$ or GND				±1		±1	μΑ
lo [‡]	$V_{CC} = 5.25 \text{ V},$	V _O = 2.5 V		-50	-100	-200	-50	-200	mA
laa	V _{CC} = 5.25 V,	I _O = 0,	Outputs high		2			3.5	mA
lcc	$V_I = V_{CC}$ or GND		Outputs low		24			33	IIIA
Ci	$V_{ } = 2.5 \text{ V or } 0.5 \text{ V}$				3				pF

[†] All typical values are at $V_{CC} = 5 \text{ V}$.

switching characteristics, C_L = 50 pF (see Figures 1 and 2)

PARAMETER	FROM	TO (OUTPUT)	V _{CC} = 5 V, T _A = 25°C			V _{CC} = 4.75 T _A = 0°	UNIT	
	(INPUT)	(OUTPUT)	MIN	TYP	MAX	MIN	MAX	
^t PLH	А	V	3.5		4.5	3.1	4.9	ns
t _{PHL}	Α	•	3.5		4.3	3.1	4.9	115
^t PLH	G	V	2		3.8	2	4	ns
^t PHL	9	·	2		3.8	2	4	115
tsk(o)				0.3	0.5		0.6	
tsk(p)	Α	Y		0.6	0.8		0.9	ns
tsk(pr)					1		1	
t _r	А	Υ					1.5	ns
t _f	А	Υ					1.5	ns

t_{pd} performance information relative to V_{CC} and temperature variation (see Note 4)

Dt _{PLH(TA)} †	Temperature drift of tpLH from 0°C to 70°C	-41 ps/10°C
Dt _{PHL(TA)} †	Temperature drift of tpHL from 0°C to 70°C	−52 ps/10°C
Dt _{PLH(VCC)} ‡	V _{CC} drift of t _{PLH} from 4.75 V to 5.25 V	28 ps/100 mV
Dt _{PHL(VCC)} ‡§	V _{CC} drift of t _{PHL} from 4.75 V to 5.25 V	20 ps/100 mV

[†] Virtually independent of V_{CC}

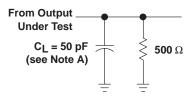
NOTE 4: The data extracted is from a wide range of characterization material.



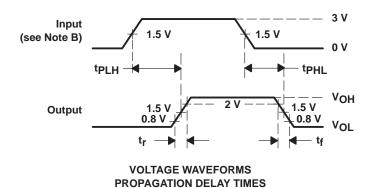
[‡]Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

[‡] Virtually independent of temperature

PARAMETER MEASUREMENT INFORMATION



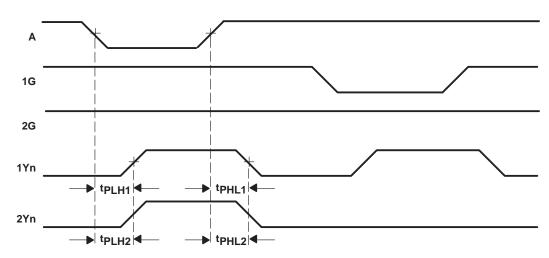
LOAD CIRCUIT



NOTES: A. C_L includes probe and jig capacitance.

B. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$, $t_f \leq$ 2.5 ns, $t_f \leq$ 2.5 ns.

Figure 1. Load Circuit and Voltage Waveforms



NOTES: A. Output skew, $t_{Sk(0)}$, is calculated as the greater of:

- The difference between the fastest and slowest of tp_{LHn} (n = 1, 2)
 The difference between the fastest and slowest of tp_{HLn} (n = 1, 2)
- B. Pulse skew, $t_{Sk(p)}$, is calculated as the greater of $|t_{PLHn} t_{PHLn}|$ (n = 1, 2).
- C. Process skew, $t_{sk(pr)}$, is calculated as the greater of:
 - The difference bétween the fastest and slowest of tpLHn (n = 1, 2) across multiple devices under identical operating conditions
 - The difference between the fastest and slowest of tpHLn (n = 1, 2) across multiple devices under identical operating conditions

Figure 2. Waveforms for Calculation of $t_{sk(o)}$, $t_{sk(p)}$, $t_{sk(pr)}$



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PACKAGING INFORMATION

Orderable part number	Status	Material type	Package Pins	Package qty Carrier	RoHS	Lead finish/	MSL rating/	Op temp (°C)	Part marking
	(1)	(2)			(3)	Ball material	Peak reflow		(6)
						(4)	(5)		
CDC341DW	Active	Production	SOIC (DW) 20	25 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	CDC341
CDC341DW.Z	Active	Production	SOIC (DW) 20	25 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	CDC341
CDC341DWG4.Z	Active	Production	SOIC (DW) 20	25 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	CDC341
CDC341DWR	Active	Production	SOIC (DW) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	CDC341
CDC341DWR.Z	Active	Production	SOIC (DW) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	CDC341

⁽¹⁾ Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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⁽²⁾ Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

⁽⁴⁾ Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

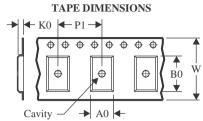
⁽⁶⁾ Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

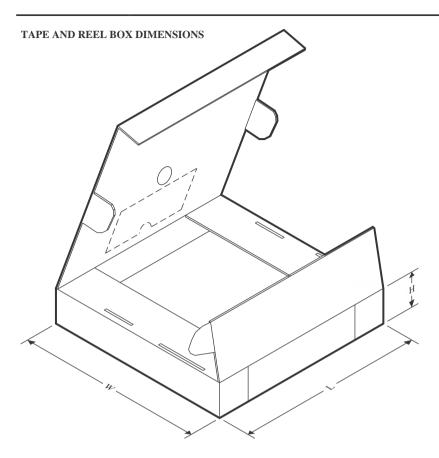


*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CDC341DW	R SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1

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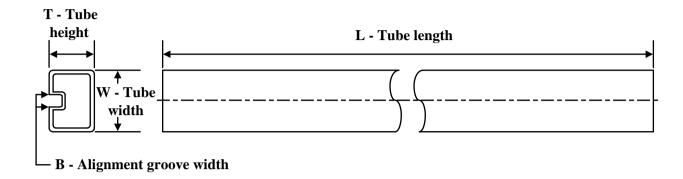
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CDC341DWR	SOIC	DW	20	2000	367.0	367.0	45.0

PACKAGE MATERIALS INFORMATION

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TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
CDC341DW	DW	SOIC	20	25	507	12.83	5080	6.6
CDC341DW.Z	DW	SOIC	20	25	507	12.83	5080	6.6
CDC341DWG4.Z	DW	SOIC	20	25	507	12.83	5080	6.6

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